

ANTREX Electronics

Electronic Components Sourcing Information

Product Reference Information

Part Number: BAP50-04W,115
Manufacturer: NXP USA Inc.
Package: SC-70, SOT-323
Availability: Please confirm with sales

Product Page:

<https://antrexco.com/product/details/nxp-usa-inc/bap50-04w-115.html>

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Note:

This PDF includes an ANTREX product reference cover page.

The original manufacturer datasheet follows from the next page.



BAP50-04W

Silicon PIN diode

Rev. 3.1 — 8 February 2019

Product data sheet

1 Product profile

1.1 General description

Two planar PIN diodes in series configuration in a SOT323 small SMD plastic package.

1.2 Features and benefits

- Two elements in series configuration in a small SMD plastic package
- Low diode capacitance
- Low diode forward resistance

1.3 Applications

- General RF application

2 Pinning information

Table 1. Discrete pinning

Pin	Description	Simplified outline	Graphic symbol
1	anode		 aaa-025249
2	cathode		
3	common connection		

3 Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
BAP50-04W	-	plastic surface-mounted package; 3 leads	SOT323

4 Marking

Table 3. Marking code

Type number	Marking code
BAP50-04W	6W%

5 Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Values are specified per diode.

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	continuous reverse voltage		-	50	V
I_F	continuous forward current		-	50	mA
P_{tot}	total power dissipation	$T_{sp} \leq 90\text{ °C}$	-	240	mW
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		-65	+150	°C

6 Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-sp)}$	thermal resistance from junction to soldering point		250	K/W

7 Characteristics

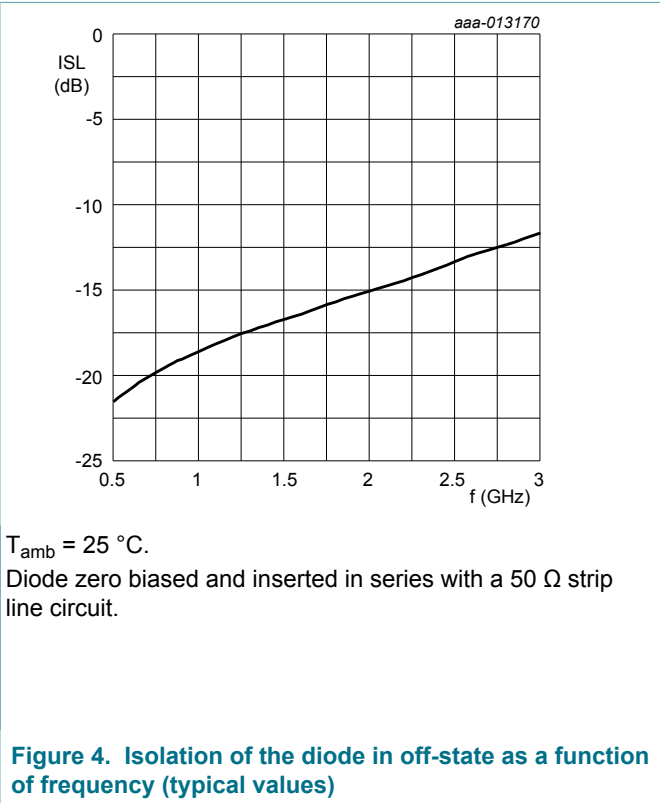
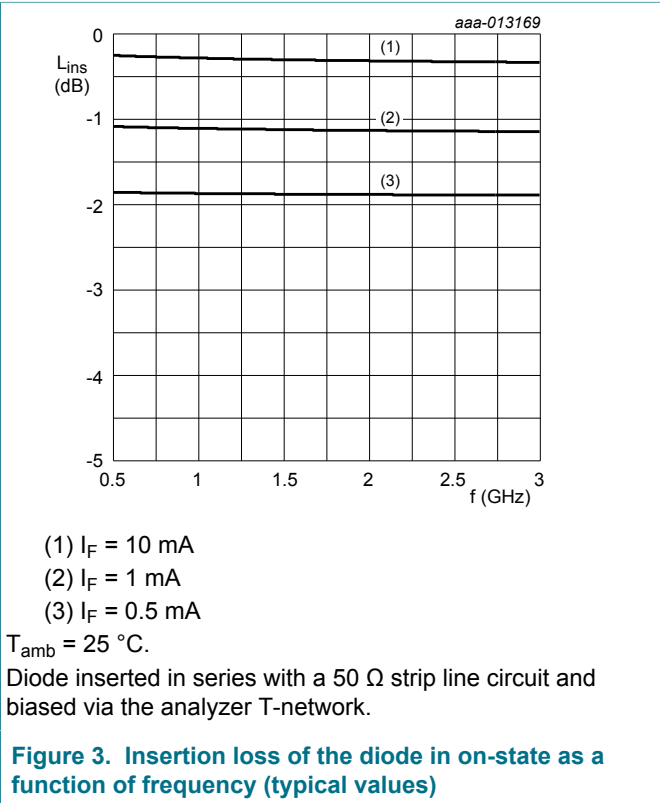
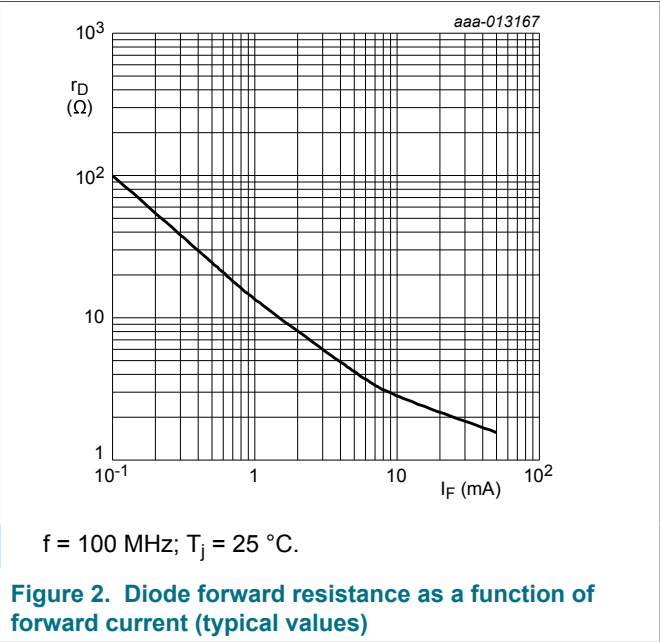
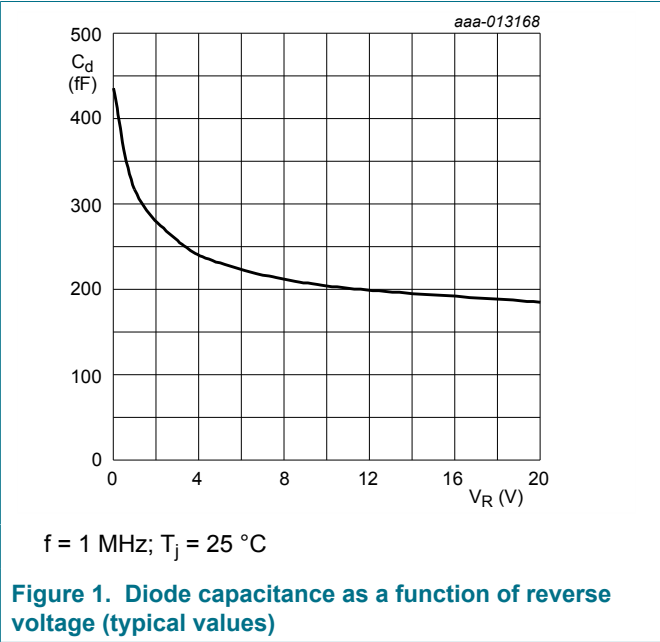
Table 6. Characteristics

$T_j = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage	$I_F = 50\text{ mA}$	-	0.95	1.1	V
V_R	reverse voltage	$I_R = 10\text{ }\mu\text{A}$	50	-	-	V
I_R	reverse current	$V_R = 50\text{ V}$	-	-	100	nA
C_d	diode capacitance	$f = 1\text{ MHz}$ (see Figure 1)				
		$V_R = 0\text{ V}$	-	0.45	-	pF
		$V_R = 1\text{ V}$	-	0.35	0.6	pF
		$V_R = 5\text{ V}$	-	0.30	0.5	pF
r_D	diode forward resistance	$f = 100\text{ MHz}$ (see Figure 2)				
		$I_F = 0.5\text{ mA}$	^[1] -	25	40	Ω
		$I_F = 1\text{ mA}$	^[1] -	14	25	Ω
		$I_F = 10\text{ mA}$	^[1] -	3	5	Ω
τ_L	charge carrier life time	when switched from $I_F = 10\text{ mA}$ to $I_R = 6\text{ mA}$; $R_L = 100\text{ }\Omega$; measured at $I_R = 3\text{ mA}$	-	1.05	-	μs
L_S	series inductance	$I_F = 10\text{ mA}$; $f = 100\text{ MHz}$	-	1.60	-	nH

[1] Guaranteed on AQL basis: inspection level S4, AQL 1.0.

8 Graphical data



9 Package outline

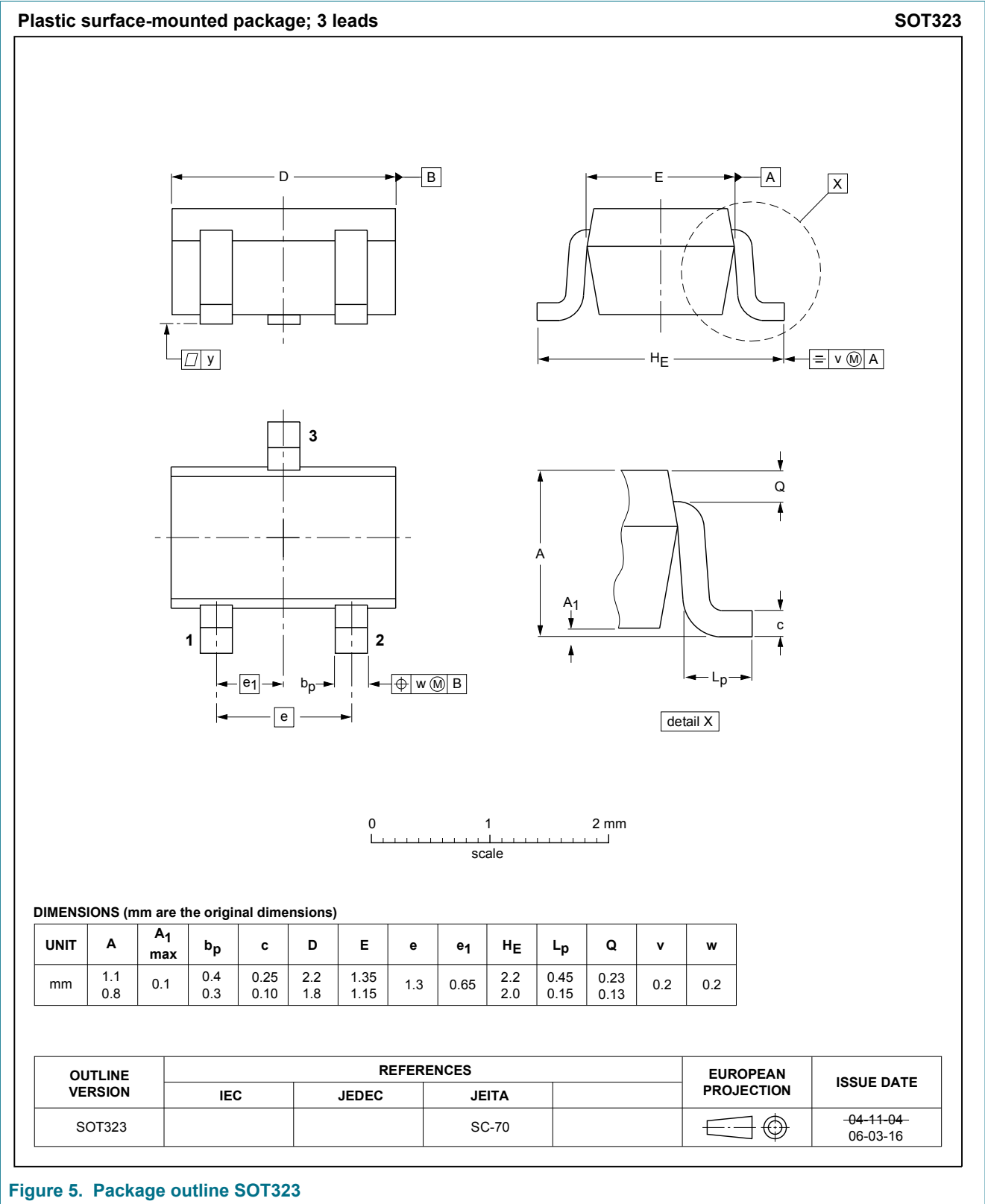


Figure 5. Package outline SOT323

10 Abbreviations

Table 7. Abbreviations

Acronym	Description
AQL	acceptable quality level
PIN	P-type, intrinsic, N-type
SMD	surface mounted-device
RF	radio frequency
S4	special inspection level 4

11 Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAP50-04W v.3.1	20190208	Product data sheet	-	BAP50-04W v.3
Modifications:	• aligned the title of the data sheet with the description on the Internet			
BAP50-04W v.3	20180323	Product data sheet	-	BAP50-04W v.2
Modifications:	• Text and graphics have changed throughout this document			
BAP50-04W v.2	20161025	Product data sheet	-	BAP50-04W_1
BAP50-04W_1	20010129	Product data sheet	-	-

12 Legal information

12.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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